

## MOSFET

### 950V CoolMOS™ PFD7 SJ Power Device

The latest 950V CoolMOS™ PFD7 series sets a new benchmark in the super junction (SJ) technologies. This technology is designed to address Lighting and Industrial SMPS applications by combining best-in-class performance with state-of-the-art ease of use. Compared to the CoolMOS™ P7 families, the PFD7 offers an integrated ultra-fast body diode enabling usage in resonant topologies with markets lowest reverse recovery charge (Q<sub>rr</sub>).

#### Features

- Integrated ultra-fast body diode
- Best-in-class reverse recovery charge Q<sub>rr</sub>
- Best-in-class FOM R<sub>DS(on)</sub> \* E<sub>oss</sub>, reduced Q<sub>g</sub>, C<sub>iss</sub>, and C<sub>oss</sub>
- Best-in-class V<sub>(GS)th</sub> of 3V and smallest V<sub>(GS)th</sub> variation of ±0.5V
- Integrated fast body diode
- Best-in-class CoolMOS™ quality and reliability
- Fully optimized portfolio
- Best-in-class R<sub>DS(on)</sub> in THD and SMD packages
- ESD protection min. Class 2 (HBM)

#### Benefits

- Excellent hard commutation robustness enabling usage in resonant topologies
- Extra safety margin for designs with increased bus voltage
- Enabling increased power density solutions
- Improved full load efficiency in industrial SMPS applications
- Price competitiveness over previous CoolMOS™ families
- Improved production yield by reducing ESD related failures

#### Potential applications

- Suitable for hard & soft switching topologies
- Optimized for usage in LLC and ZVS topologies
- PFC & LLC applications in Lighting and Industrial SMPS

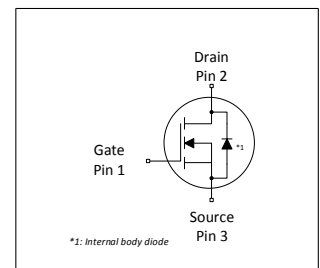
#### Product validation

Fully qualified according to JEDEC for Industrial Applications

**Table 1 Key Performance Parameters**

| Parameter                                | Value | Unit |
|--|-------|------|
| V <sub>DS</sub> @ T <sub>j</sub> = 25 °C | 950   | V    |
| R <sub>DS(on),max</sub>                  | 450   | mΩ   |
| Q <sub>g,typ</sub>                       | 43    | nC   |
| I <sub>D</sub>                           | 7.2   | A    |
| E <sub>oss</sub> @ 500V                  | 3.0   | μJ   |
| Body diode di <sub>F</sub> /dt           | 1300  | A/μs |
| Q <sub>oss</sub> @ 500V                  | 0.1   | μC   |

| Type / Ordering Code | Package          | Marking  | Related Links  |
|----------------------|------------------|----------|----------------|
| IPA95R450PFD7        | PG-TO220 FullPAK | 95R450D7 | see Appendix A |



RoHS

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## 1 Maximum ratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

| Parameter                              | Symbol              | Values |      |            | Unit             | Note / Test Condition   |
|--|---------------------|--------|------|------------|------------------|---|
|  |                     | Min.   | Typ. | Max.       |                  |   |
| Continuous drain current <sup>1)</sup> | $I_D$               | -      | -    | 7.2<br>4.5 | A                | $T_C=25^\circ\text{C}$<br>$T_C=100^\circ\text{C}$   |
| Pulsed drain current <sup>2)</sup>     | $I_{D,pulse}$       | -      | -    | 43         | A                | $T_C=25^\circ\text{C}$  |
| Avalanche energy, single pulse         | $E_{AS}$            | -      | -    | 29         | mJ               | $I_D=1.8\text{A}$ ; $V_{DD}=50\text{V}$ ; see table 10                                      |
| Avalanche energy, repetitive           | $E_{AR}$            | -      | -    | 0.22       | mJ               | $I_D=1.8\text{A}$ ; $V_{DD}=50\text{V}$ ; see table 10                                      |
| Avalanche current, single pulse        | $I_{AS}$            | -      | -    | 1.8        | A                | -   |
| MOSFET dv/dt ruggedness                | dv/dt               | -      | -    | 120        | V/ns             | $V_{DS}=0\dots400\text{V}$  |
| Gate source voltage (static)           | $V_{GS}$            | -20    | -    | 20         | V                | static;   |
| Gate source voltage (dynamic)          | $V_{GS}$            | -30    | -    | 30         | V                | AC ( $f>1\text{ Hz}$ )  |
| Power dissipation                      | $P_{tot}$           | -      | -    | 30         | W                | $T_C=25^\circ\text{C}$  |
| Storage temperature                    | $T_{stg}$           | -55    | -    | 150        | $^\circ\text{C}$ | -   |
| Operating junction temperature         | $T_j$               | -55    | -    | 150        | $^\circ\text{C}$ | -   |
| Mounting torque                        | -                   | -      | -    | 50         | Ncm              | M2.5 screws   |
| Continuous diode forward current       | $I_S$               | -      | -    | 5          | A                | $T_C=25^\circ\text{C}$  |
| Diode pulse current <sup>2)</sup>      | $I_{S,pulse}$       | -      | -    | 43         | A                | $T_C=25^\circ\text{C}$  |
| Reverse diode dv/dt <sup>3)</sup>      | dv/dt               | -      | -    | 70         | V/ns             | $V_{DS}=0\dots400\text{V}$ , $I_{SD}\leq 5\text{A}$ , $T_j=25^\circ\text{C}$<br>see table 8 |
| Maximum diode commutation speed        | di <sub>F</sub> /dt | -      | -    | 1300       | A/ $\mu\text{s}$ | $V_{DS}=0\dots400\text{V}$ , $I_{SD}\leq 5\text{A}$ , $T_j=25^\circ\text{C}$<br>see table 8 |
| Insulation withstand voltage           | $V_{ISO}$           | -      | -    | 2500       | V                | $V_{rms}$ , $T_C=25^\circ\text{C}$ , $t=1\text{min}$  |

<sup>1)</sup> Limited by  $T_{j,max}$ . Maximum Duty Cycle  $D = 0.50$

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup> Identical low side and high side switch with identical  $R_\theta$

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

| Parameter  | Symbol     | Values |      |      | Unit | Note / Test Condition               |
|--|------------|--------|------|------|------|-------------------------------------|
|  |            | Min.   | Typ. | Max. |      |                                     |
| Thermal resistance, junction - case                        | $R_{thJC}$ | -      | -    | 4.10 | °C/W | -                                   |
| Thermal resistance, junction - ambient                     | $R_{thJA}$ | -      | -    | 62   | °C/W | leaded                              |
| Thermal resistance, junction - ambient for SMD version     | $R_{thJA}$ | -      | -    | -    | °C/W | n.a.                                |
| Soldering temperature, wavesoldering only allowed at leads | $T_{sold}$ | -      | -    | 260  | °C   | 1.6mm (0.063 in.) from case for 10s |

### 3 Electrical characteristics

at  $T_j=25^\circ\text{C}$ , unless otherwise specified

**Table 4 Static characteristics**

| Parameter                        | Symbol        | Values |              |           | Unit          | Note / Test Condition   |
|----------------------------------|---------------|--------|--------------|-----------|---------------|---|
|                                  |               | Min.   | Typ.         | Max.      |               |   |
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | 950    | -            | -         | V             | $V_{GS}=0V, I_D=1mA$  |
| Gate threshold voltage           | $V_{(GS)th}$  | 2.5    | 3            | 3.5       | V             | $V_{DS}=V_{GS}, I_D=0.36mA$   |
| Zero gate voltage drain current  | $I_{DSS}$     | -      | -            | 1         | $\mu\text{A}$ | $V_{DS}=950V, V_{GS}=0V, T_j=25^\circ\text{C}$<br>$V_{DS}=950V, V_{GS}=0V, T_j=150^\circ\text{C}$ |
| Gate-source leakage current      | $I_{GSS}$     | -      | -            | 100       | nA            | $V_{GS}=20V, V_{DS}=0V$   |
| Drain-source on-state resistance | $R_{DS(on)}$  | -      | 0.35<br>0.93 | 0.45<br>- | $\Omega$      | $V_{GS}=10V, I_D=7.2A, T_j=25^\circ\text{C}$<br>$V_{GS}=10V, I_D=7.2A, T_j=150^\circ\text{C}$     |
| Gate resistance                  | $R_G$         | -      | 1            | -         | $\Omega$      | $f=250kHz$ , open drain   |

**Table 5 Dynamic characteristics**

| Parameter  | Symbol       | Values |      |      | Unit | Note / Test Condition   |
|--|--------------|--------|------|------|------|---|
|  |              | Min.   | Typ. | Max. |      |   |
| Input capacitance  | $C_{iss}$    | -      | 1230 | -    | pF   | $V_{GS}=0V, V_{DS}=400V, f=250kHz$                                    |
| Output capacitance   | $C_{oss}$    | -      | 17   | -    | pF   | $V_{GS}=0V, V_{DS}=400V, f=250kHz$                                    |
| Effective output capacitance, energy related <sup>1)</sup> | $C_{o(er)}$  | -      | 28   | -    | pF   | $V_{GS}=0V, V_{DS}=0...400V$  |
| Effective output capacitance, time related <sup>2)</sup>   | $C_{o(tr)}$  | -      | 277  | -    | pF   | $I_D=constant, V_{GS}=0V, V_{DS}=0...400V$                            |
| Turn-on delay time   | $t_{d(on)}$  | -      | 9    | -    | ns   | $V_{DD}=400V, V_{GS}=13V, I_D=7.2A,$<br>$R_G=5.3\Omega$ ; see table 9 |
| Rise time  | $t_r$        | -      | 8.7  | -    | ns   | $V_{DD}=400V, V_{GS}=13V, I_D=7.2A,$<br>$R_G=5.3\Omega$ ; see table 9 |
| Turn-off delay time  | $t_{d(off)}$ | -      | 45   | -    | ns   | $V_{DD}=400V, V_{GS}=13V, I_D=7.2A,$<br>$R_G=5.3\Omega$ ; see table 9 |
| Fall time  | $t_f$        | -      | 4.7  | -    | ns   | $V_{DD}=400V, V_{GS}=13V, I_D=7.2A,$<br>$R_G=5.3\Omega$ ; see table 9 |

**Table 6 Gate charge characteristics**

| Parameter             | Symbol        | Values |      |      | Unit | Note / Test Condition                    |
|-----------------------|---------------|--------|------|------|------|--|
|                       |               | Min.   | Typ. | Max. |      |  |
| Gate to source charge | $Q_{gs}$      | -      | 6    | -    | nC   | $V_{DD}=760V, I_D=7.2A, V_{GS}=0$ to 10V |
| Gate to drain charge  | $Q_{gd}$      | -      | 13   | -    | nC   | $V_{DD}=760V, I_D=7.2A, V_{GS}=0$ to 10V |
| Gate charge total     | $Q_g$         | -      | 43   | -    | nC   | $V_{DD}=760V, I_D=7.2A, V_{GS}=0$ to 10V |
| Gate plateau voltage  | $V_{plateau}$ | -      | 4.5  | -    | V    | $V_{DD}=760V, I_D=7.2A, V_{GS}=0$ to 10V |

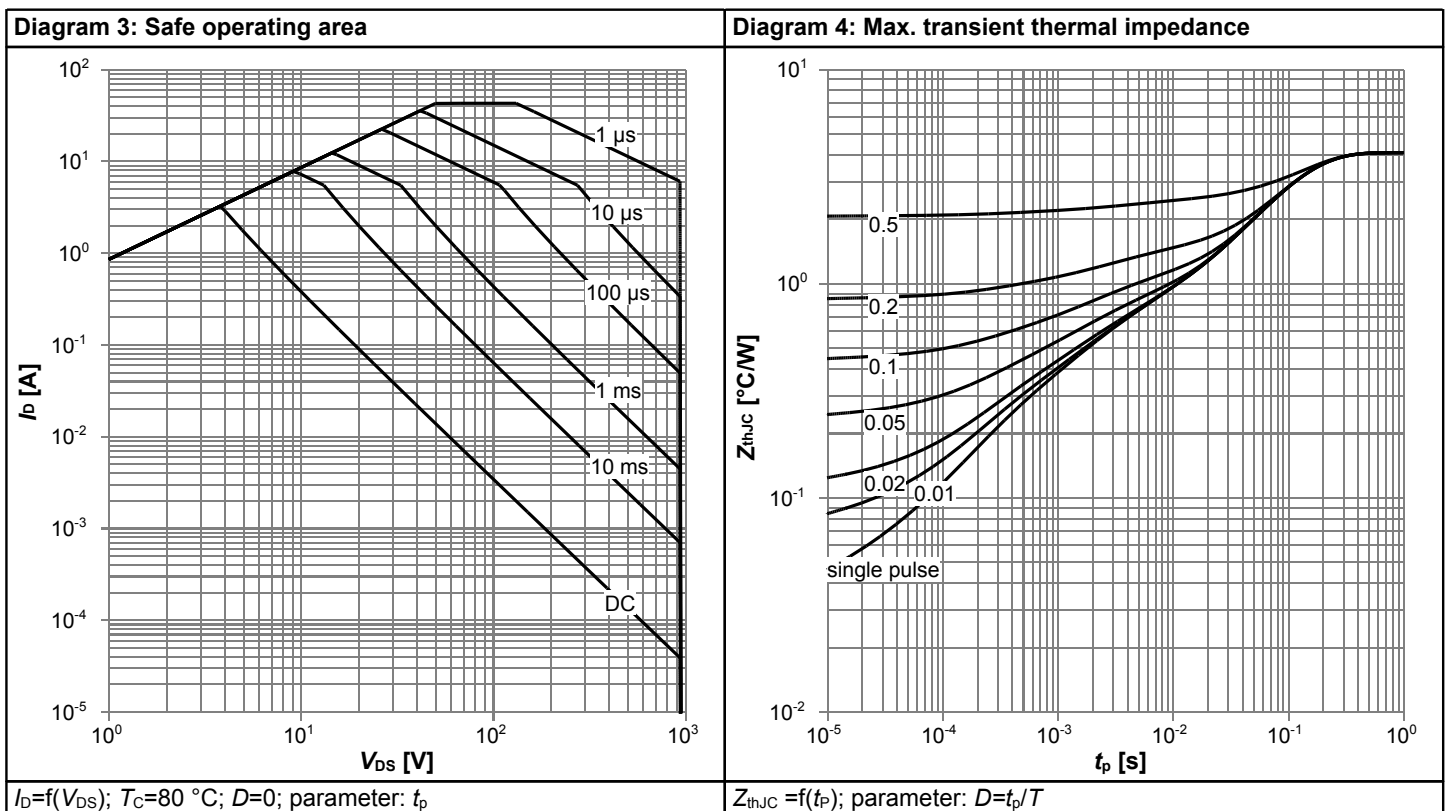
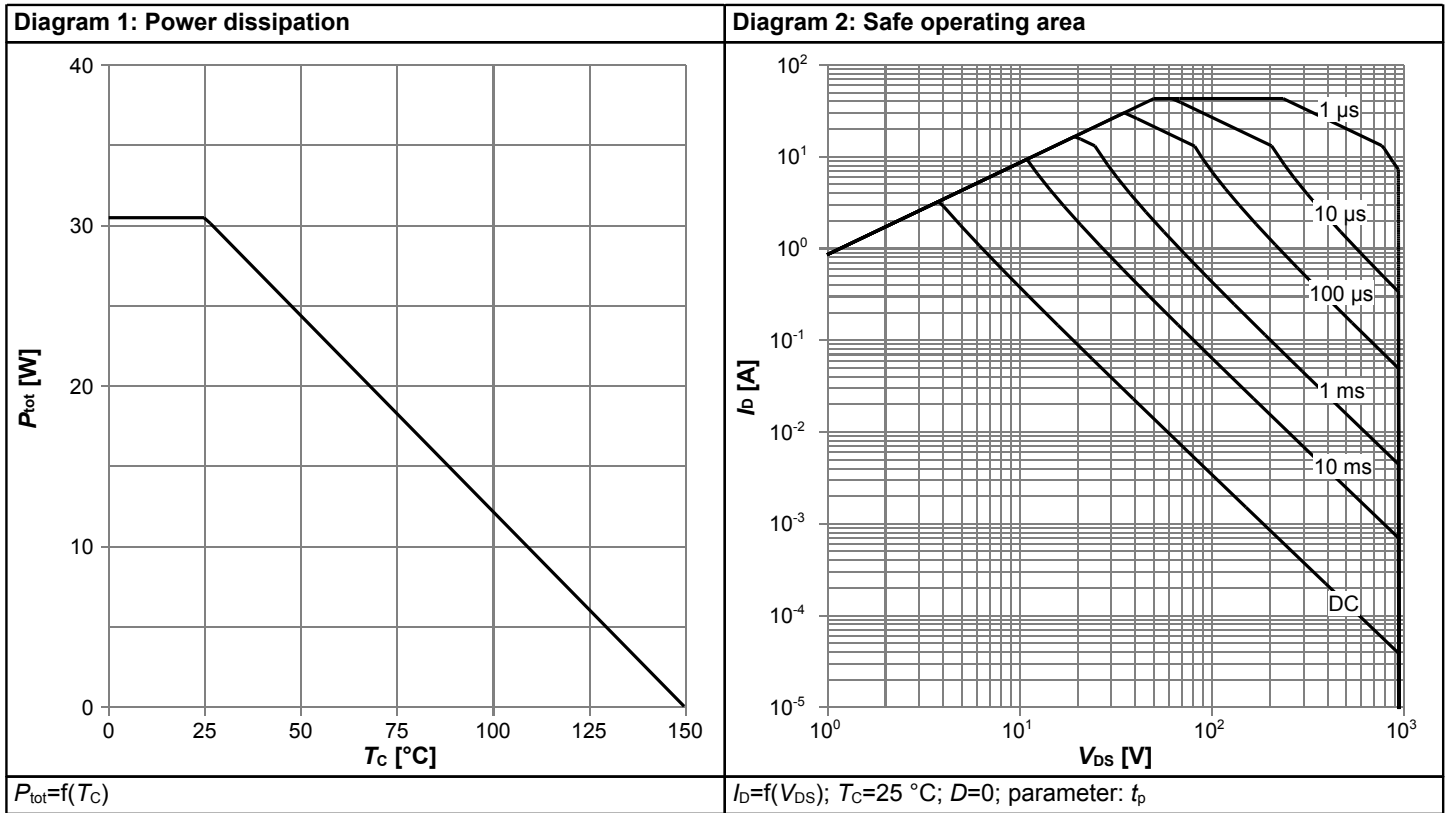
<sup>1)</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 400V

<sup>2)</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 400V

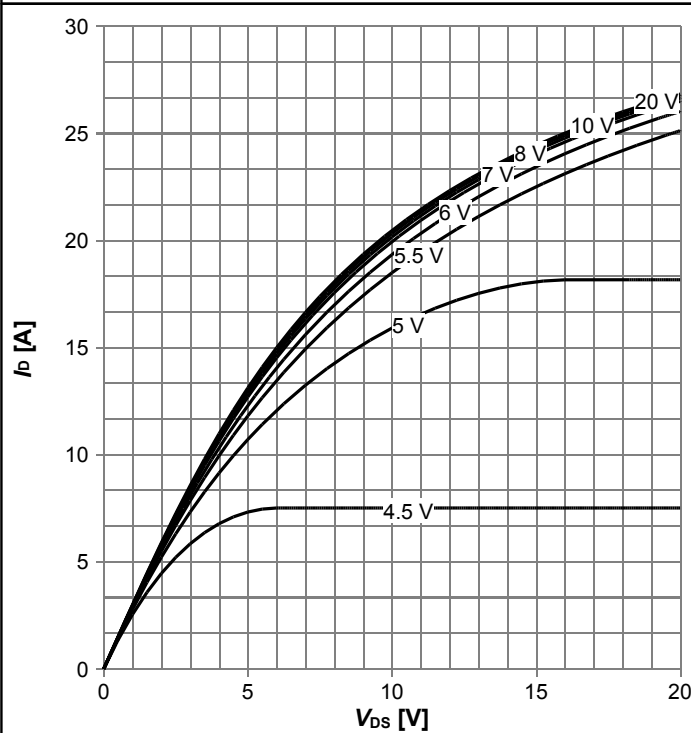
**Table 7 Reverse diode characteristics**

| Parameter                     | Symbol    | Values |      |      | Unit    | Note / Test Condition                                     |
|-------------------------------|-----------|--------|------|------|---------|---|
|                               |           | Min.   | Typ. | Max. |         |   |
| Diode forward voltage         | $V_{SD}$  | -      | 1.1  | -    | V       | $V_{GS}=0V, I_F=7.2A, T_j=25^\circ C$                     |
| Reverse recovery time         | $t_{rr}$  | -      | 149  | -    | ns      | $V_R=400V, I_F=7.2A, di_F/dt=100A/\mu s$ ;<br>see table 8 |
| Reverse recovery charge       | $Q_{rr}$  | -      | 0.72 | -    | $\mu C$ | $V_R=400V, I_F=7.2A, di_F/dt=100A/\mu s$ ;<br>see table 8 |
| Peak reverse recovery current | $I_{rrm}$ | -      | 9.3  | -    | A       | $V_R=400V, I_F=7.2A, di_F/dt=100A/\mu s$ ;<br>see table 8 |

### 4 Electrical characteristics diagrams

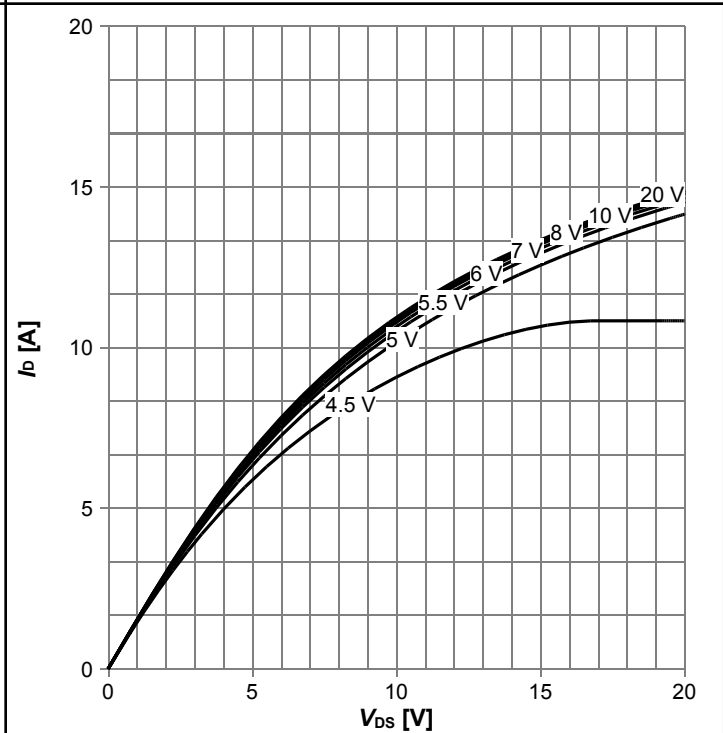


**Diagram 5: Typ. output characteristics**



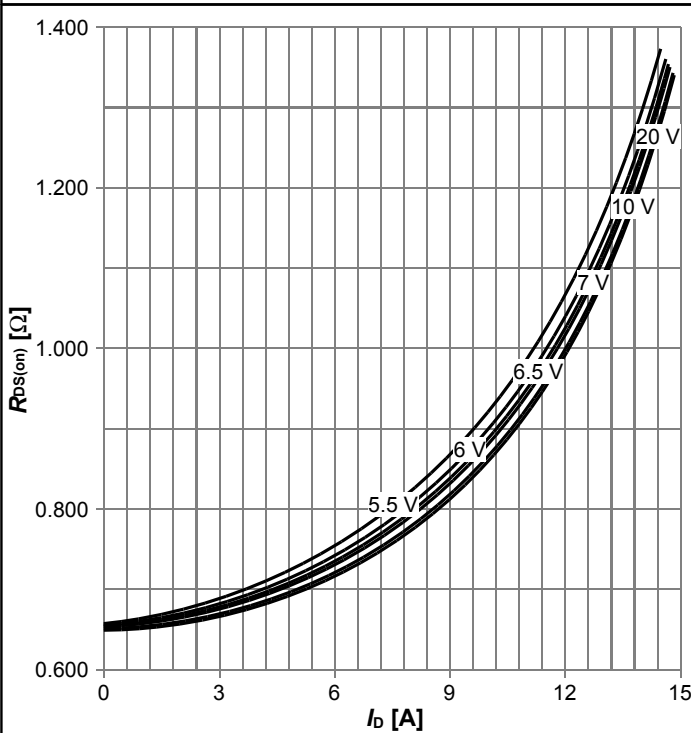
$I_D=f(V_{DS}); T_j=25\text{ °C};$  parameter:  $V_{GS}$

**Diagram 6: Typ. output characteristics**



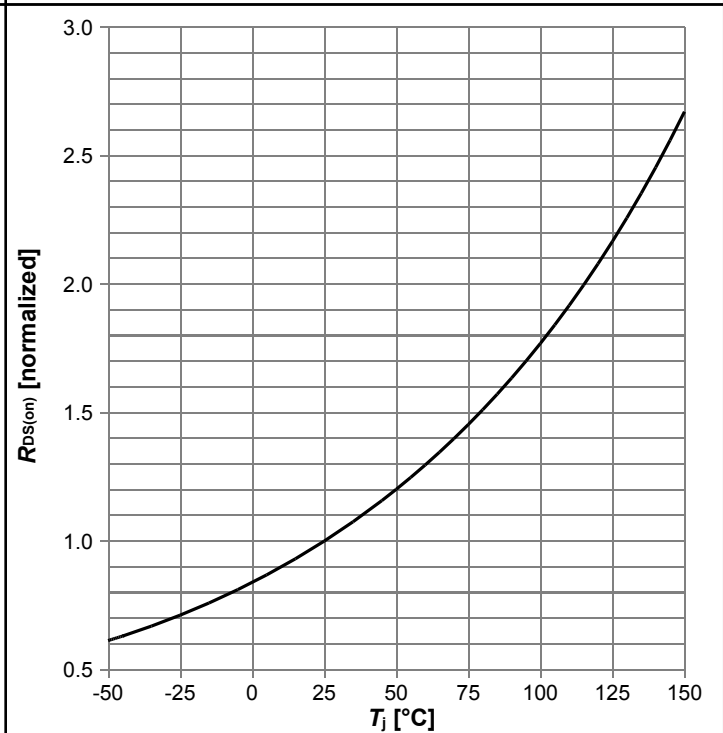
$I_D=f(V_{DS}); T_j=125\text{ °C};$  parameter:  $V_{GS}$

**Diagram 7: Typ. drain-source on-state resistance**



$R_{DS(on)}=f(I_D); T_j=125\text{ °C};$  parameter:  $V_{GS}$

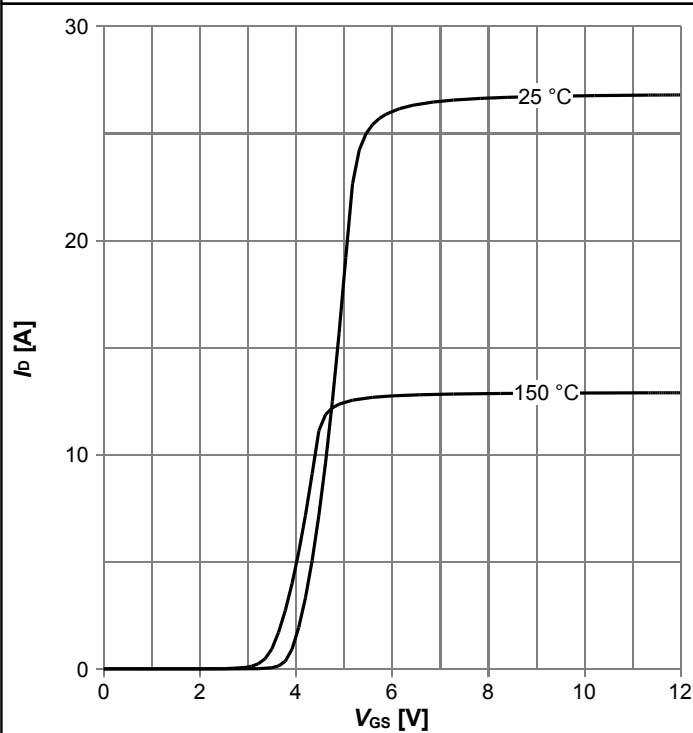
**Diagram 8: Drain-source on-state resistance**



$R_{DS(on)}=f(T_j); I_D=7.2\text{ A}; V_{GS}=10\text{ V}$

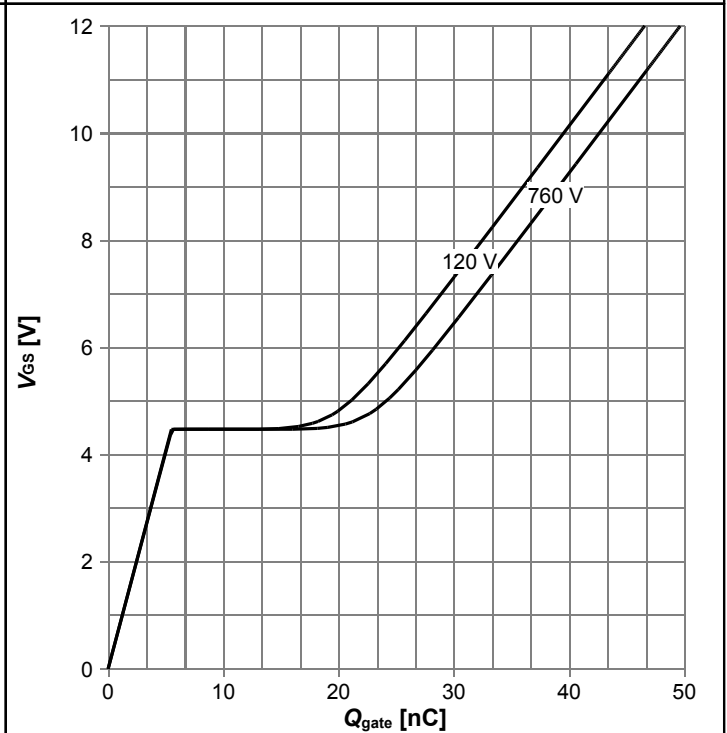


Diagram 9: Typ. transfer characteristics



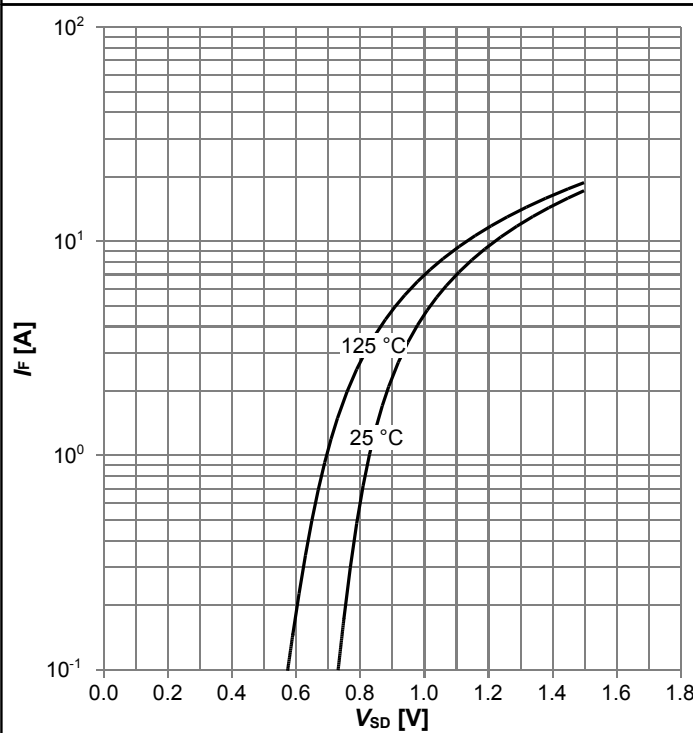
$I_D = f(V_{GS})$ ;  $V_{DS} = 20V$ ; parameter:  $T_j$

Diagram 10: Typ. gate charge



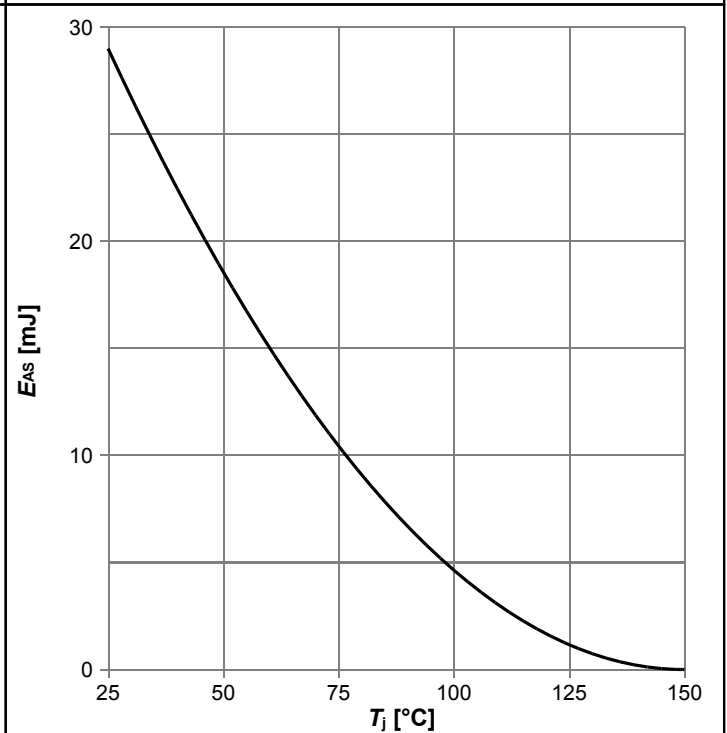
$V_{GS} = f(Q_{gate})$ ;  $I_D = 7.2 A$  pulsed; parameter:  $V_{DD}$

Diagram 11: Forward characteristics of reverse diode



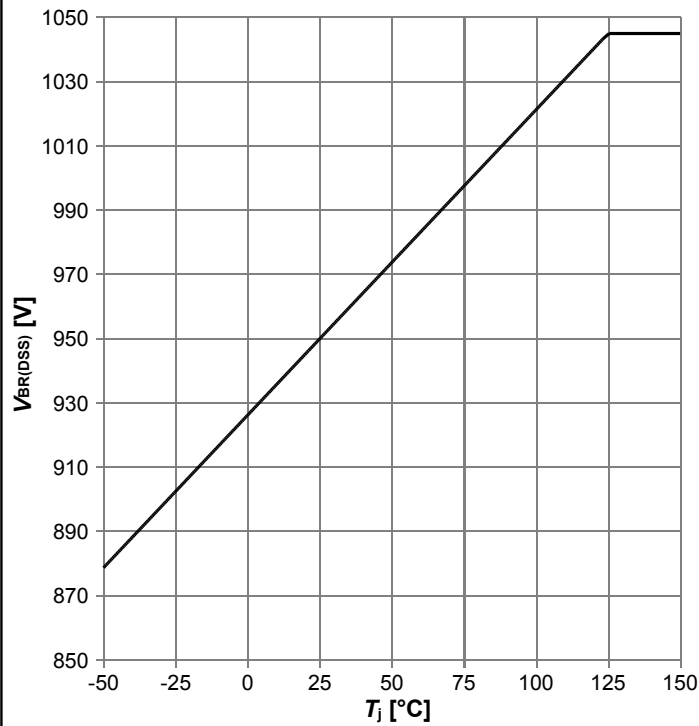
$I_F = f(V_{SD})$ ; parameter:  $T_j$

Diagram 12: Avalanche energy



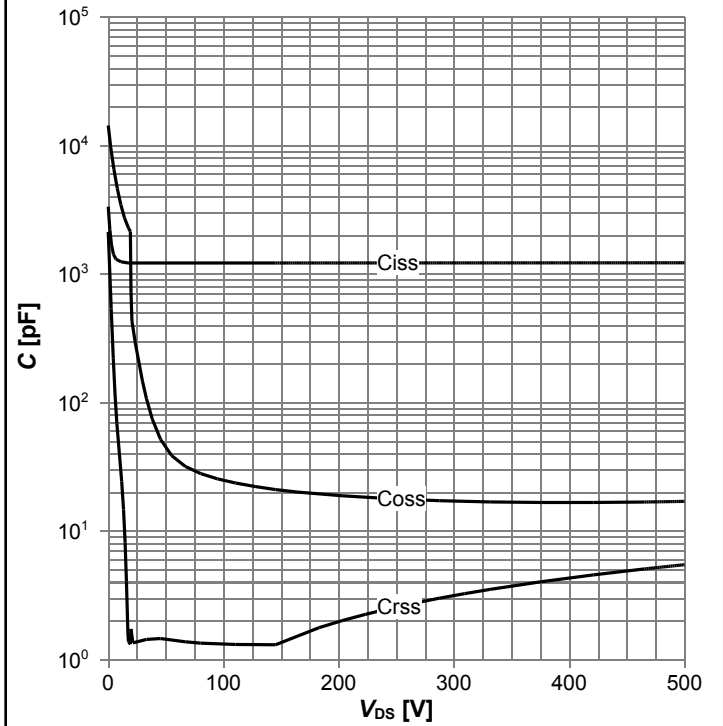
$E_{AS} = f(T_j)$ ;  $I_D = 1.8 A$ ;  $V_{DD} = 50 V$

**Diagram 13: Drain-source breakdown voltage**



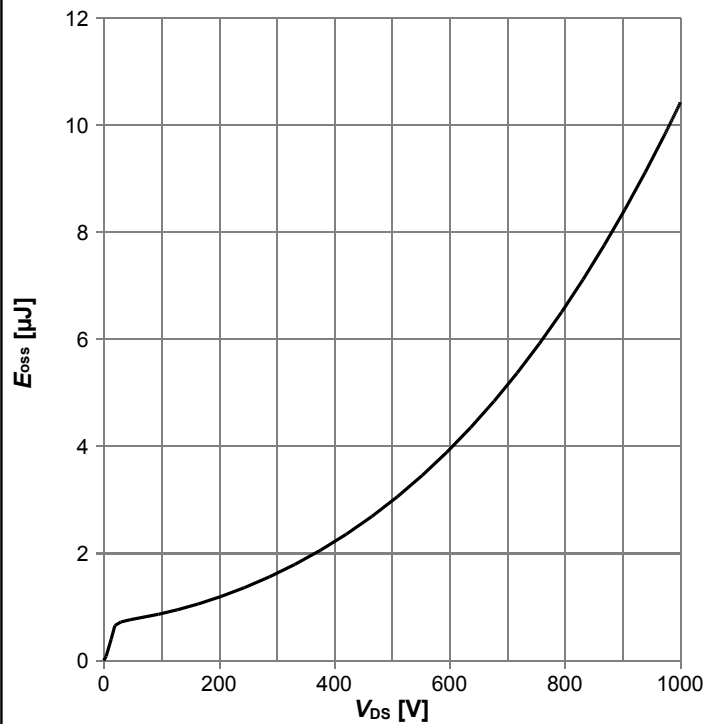
$V_{BR(DSS)}=f(T_j); I_D=1\text{ mA}$

**Diagram 14: Typ. capacitances**



$C=f(V_{DS}); V_{GS}=0\text{ V}; f=250\text{ kHz}$

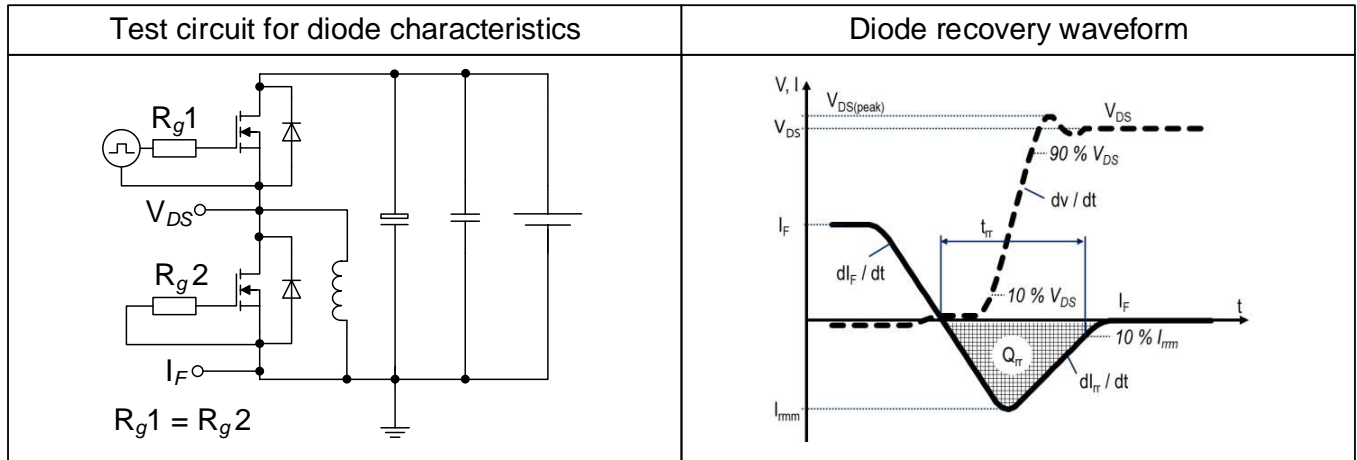
**Diagram 15: Typ. Coss stored energy**



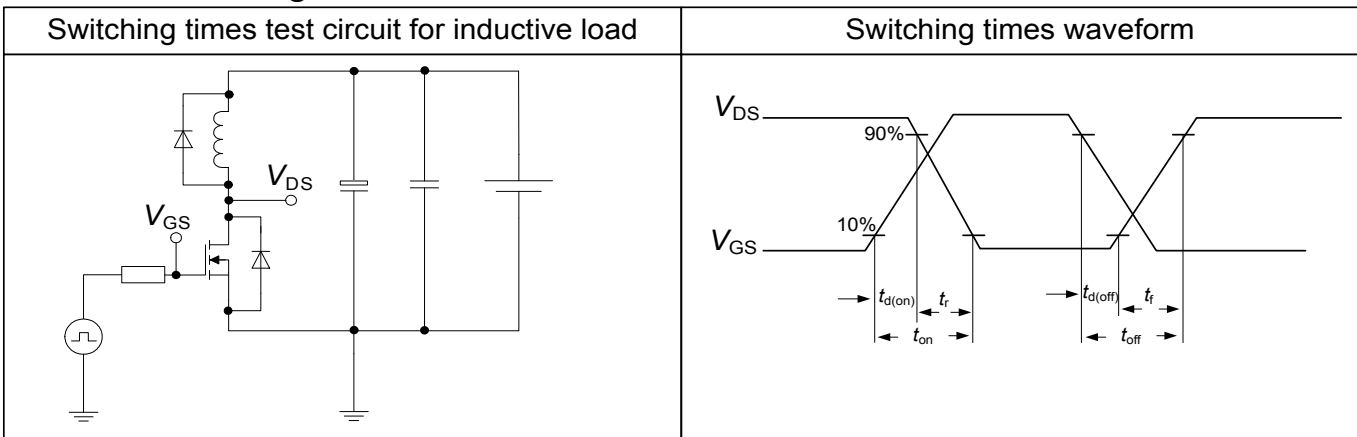
$E_{oss}=f(V_{DS})$

## 5 Test Circuits

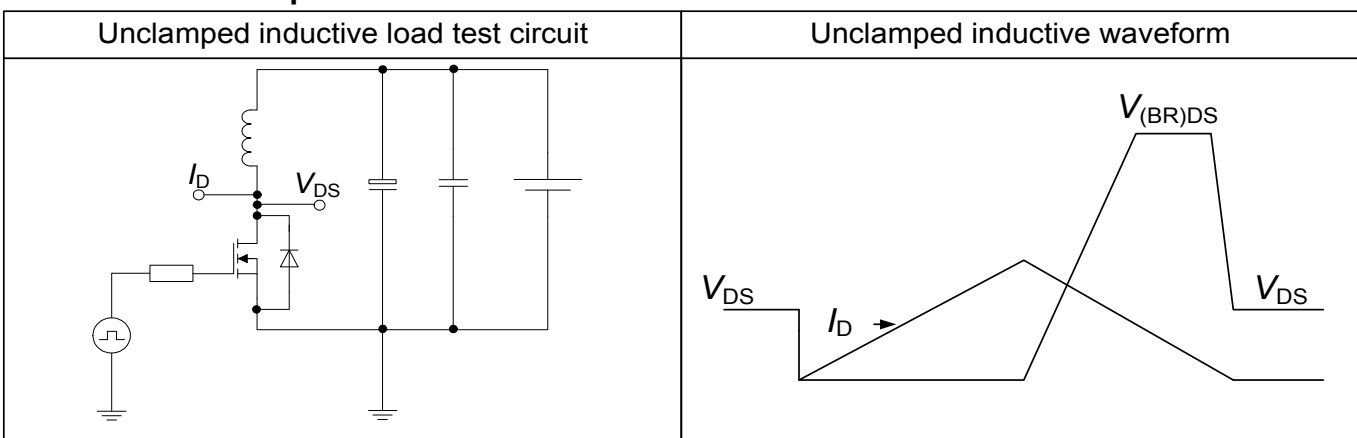
**Table 8 Diode characteristics**



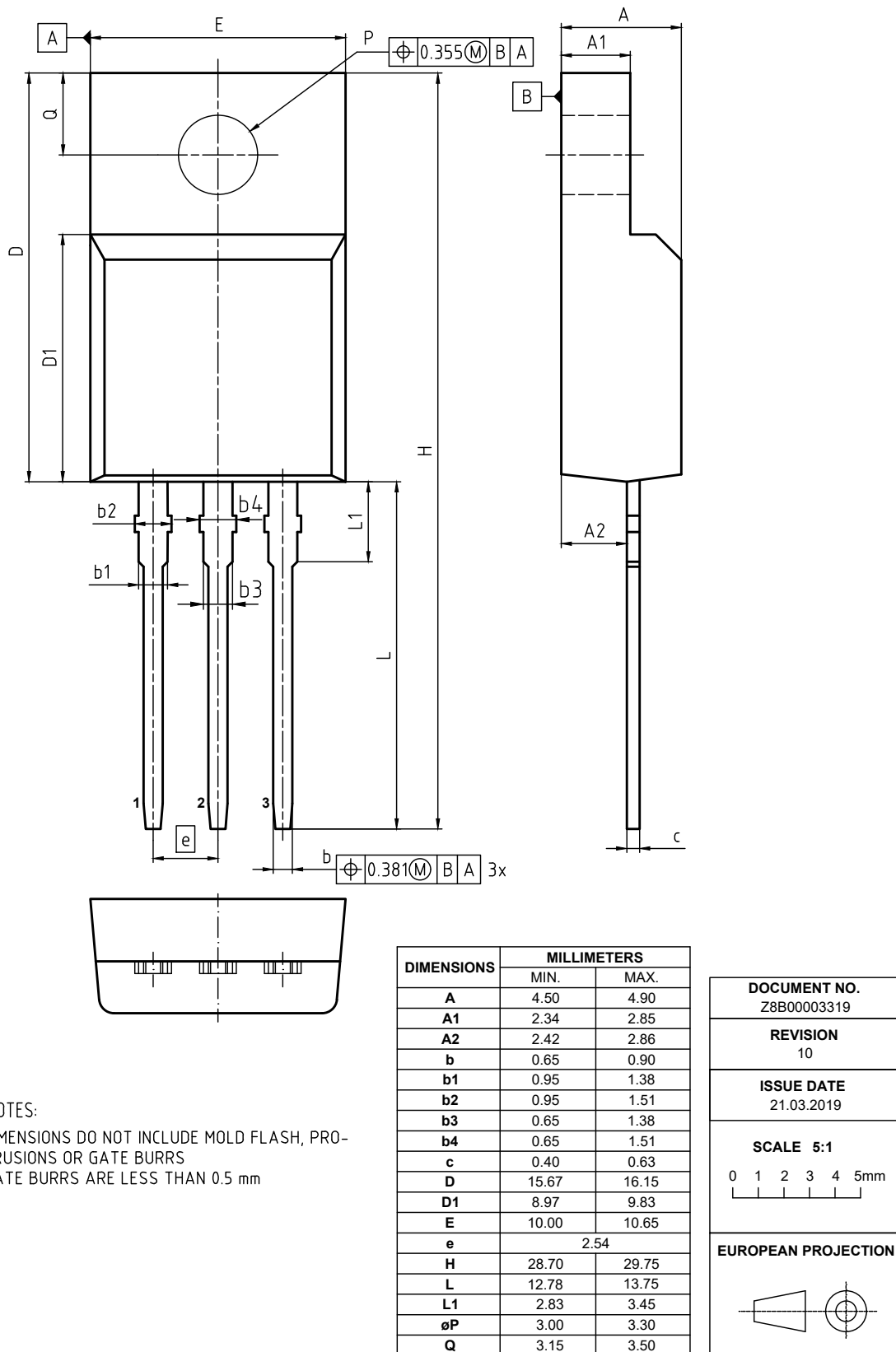
**Table 9 Switching times**



**Table 10 Unclamped inductive load**



## 6 Package Outlines



**Figure 1 Outline PG-TO220 FullPAK, dimensions in mm**

## 7 Appendix A

### Table 11 Related Links

- IFX CoolMOS PFD7 950V Webpage: [www.infineon.com](http://www.infineon.com)
- IFX CoolMOS PFD7 950V application note: [www.infineon.com](http://www.infineon.com)
- IFX CoolMOS PFD7 950V simulation model: [www.infineon.com](http://www.infineon.com)
- IFX Design tools: [www.infineon.com](http://www.infineon.com)

## Revision History

IPA95R450PFD7

**Revision: 2022-04-22, Rev. 2.1**

Previous Revision

| Revision | Date       | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.0      | 2022-03-19 | Release of final version                     |
| 2.1      | 2022-04-22 | Modified features                            |

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